resistance of thermal transducer 156 can be monitored. To improve the aerodynamic performance, steps 164, 166 are located near front edge 168 of glide head 132. The contoured features on the air bearing surface can be varied to achieve a desired aerodynamic performance of the glide head.

Please amend the paragraph beginning on Page 13, lines 3-16 as follows:

An embodiment of glide head 132 with different types of defect detecting transducers is depicted in Fig. 7. Glide head 132 includes rails 400, 402 along air bearing surface 404 which form raised bearing surfaces 403-1, 403-2 as shown in Fig. 7 which are elevated above surface 404. Thermal transducer 406 is located on rail 402 along the raised bearing surface 403-2. Electrically conductive pads 408, 410 provide electrical conduction between transducer 406 and the top surface 412 of glide head 132. Pads 408, 410 are connected to resistance measurement circuit 414 for the evaluation of changes in resistance of the transducer 406. Pads 408, 410 are located along or near rear edge 416 of glide head 132. Piezoelectric transducer 420 is located on wing 422 along top surface 412. Piezoelectric transducer 420 is connected to measurement circuit 424.

Please amend the paragraph beginning on Page 13, line 29 and ending on Page 14, line 3 as follows:

The order of processing depends on the approach used to produce the slider from a wafer. In conventional approaches, the air bearing surface is formed from a cut edge of the wafer. In these approaches, the electrically conductive pads can be deposited on the surface of the wafer prior to the slicing of the

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wafer. The pads are positioned on the wafer surface such that they are along the rear edge of the slider after or glide head the sliders are cut from the wafer.

Please amend the paragraph beginning on Page 14, line 30, and ending on Page 15, line 4 as follows:

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To form the sliders with the thermal transducers located on the air bearing surface (e.g. raised bearing surfaces), a plurality of thermal transducers 500 can be applied along the smooth surface 502 of wafer 504, as shown in Fig. 8. Thermal transducers 500 are located or formed on the raised bearing surfaces 508 of rails 506 contoured onto surface 502 to form a surface portion 509 extending along a portion of the raised surface 508 of rail 506 and a thickness portion 514 as illustrated in Fig. 10. Representative rails 506 are noted in Fig. 8. Alternatively, as previously explained, thermal transducers 500 can be formed on the raised contoured surface or rails of the air bearing surface on a bar sliced from the wafer. As shown in FIG. 10, the thermal transducers 500 can be covered with a protective layer 516, such as diamond-like carbon. Additional transducers such as a piezoelectric transducer also can be placed on the opposite surface of the wafer prior to the slicing into individual sliders.